



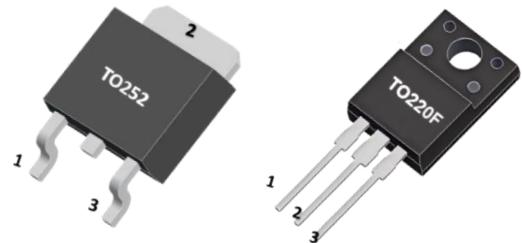
HY30N06

N-CHANNEL POWER MOSFET

30A, 60V N-CHANNEL ENHANCEMENT MODE POWER MOSFET

■ DESCRIPTION

The HY30N06A is a low voltage power MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and excellent avalanche characteristics. This power MOSFET is usually used at automotive applications in power supplies, high efficient DC to DC converters and battery operated products.



■ FEATURE

- * RDS(ON) = 40m Ω@VGS = 10 V, ID=15A
- * Ultra low gate charge (typical 20nC)
- * Low reverse transfer Capacitance (CRSS = typical 80 pF)
- * Fast switching capability
- * Avalanche energy specified
- * Improved dv/dt capability

■ MARKING



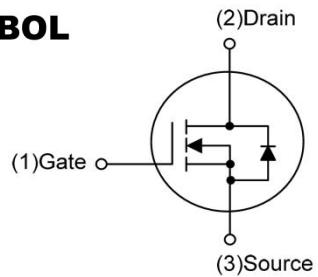
: HY LOGO

HY30N06A=Device Code

XXXX=Date Code

Solid Dot=Green molding compound

■ SYMBOL



■ ABSOLUTE MAXIMUM RATINGS(TA=25°C, unless otherwise specified.)

SYMBOL	PARAMETER		VALUE	UNIT
V _{DSS}	Drain-Source Voltage		60	V
V _{GSS}	Gate Source Voltage		±20	V
I _D	Continuous Drain Current	T _C = 25°C	30	A
		T _C = 125°C	21.3	
I _{DM}	Pulsed Drain Current (Note 2)		120	A
E _A	Avalanche Energy	Single Pulsed (Note 3)	300	mJ
E _{AR}		Repetitive (Note 2)	8	mJ
P _D	Maximum Power Dissipation	TO-220F	45	W
		TO-252	46	
T _J	Storage Temperature		150	°C
T _{TSG}	Storage Temperature		-55~150	°C
T _{TOPR}	Operation Temperature		-55~150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repeatability rating: pulse width limited by junction temperature

3. L=0.66mH, I_{AS}=30A, V_{DD}=25V, R_G=20Ω, Starting T_J=25°C



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■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT		
Junction-to-Ambient	TO-220F	R _{θJA}	62.5	°C/W		
	TO-252		110			
Junction-to-Case	TO-220F	R _{θJC}	2.7	°C/W		
	TO-252		2.85			

■ ELECTRICAL CHARACTERISTICS (TA=25°C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	60			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =60V, V _{GS} =0V			10	μA
Gate-body leakage current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V			±100	nA
Breakdown Voltage Temperature Coefficient	△V _{(BR) DSS} /△T _J	I _D =250μA, Referenced to 25°C		0.06		V/°C
ON CHARACTERISTICS						
Drain-source on-state resistance	R _{DSON}	V _{GS} =10V, I _D =15A		32	40	mΩ
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} =V _{DS} , I _D =250μA	2.0		4.0	V
DYNAMIC PARAMETERS						
Input Capacitance	C _{ISS}	V _{GS} =0V, V _{DS} =25V f=1.0MHz		800		pF
Output Capacitance	C _{OSS}			300		
Reverse Transfer Capacitance	C _{rss}			50		
SWITCHING PARAMETERS						
Total gate charge	Q _g	V _{DS} =60V, V _{GS} =10V I _D =24A(Note 1, 2)		20	30	nC
Gate-source charge	Q _{gs}			6		
Gate-drain charge	Q _{gd}			9		
Turn-On Delay Time	t _{d(on)}	V _{DD} =30V, I _D = 24A V _{GS} =10V(Note 1, 2)		52		nS
Turn-On Rise time	t _r			96		
Turn-Off Delay Time	t _{d(off)}			124		
Turn-Off Fall time	t _f			84		
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Continuous drain-source diode forward current	I _s				30	A
Pulsed drain-source diode forward current	I _{SM}				120	A
Drain-source diode forward voltage	V _{SD}	I _F =30A, V _{GS} =0V			1.4	V

Notes:

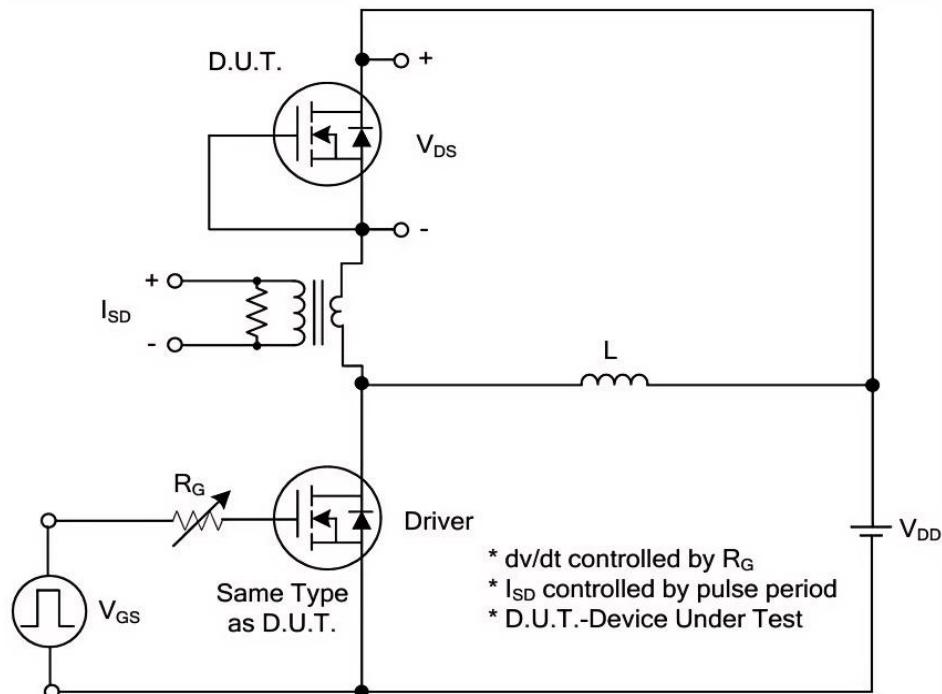
1. Pulse Test: Pulse width ≤ 300μs, Duty cycle ≤ 2% .
2. Essentially independent of operating temperature .



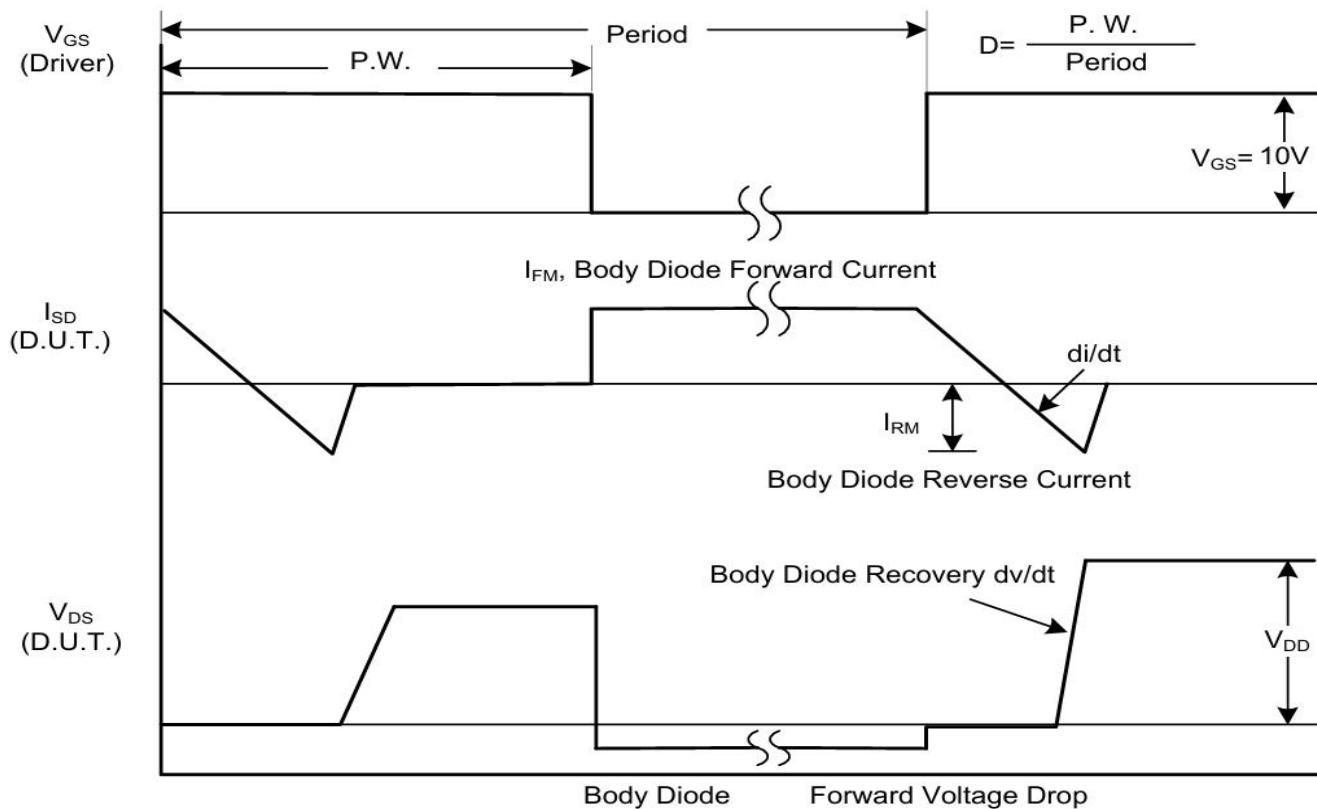
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■ TEST CIRCUITS AND WAVEFORMS



Peak Diode Recovery dv/dt Test Circuit



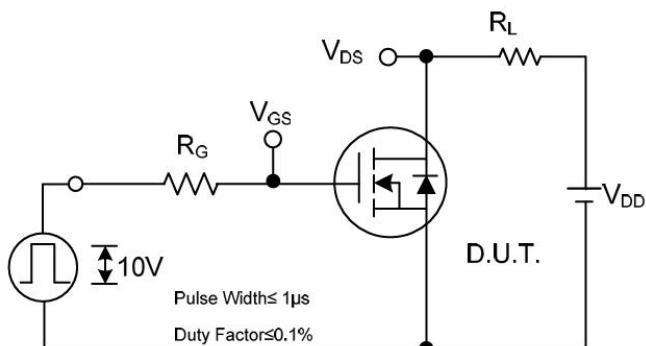
Peak Diode Recovery dv/dt Waveforms



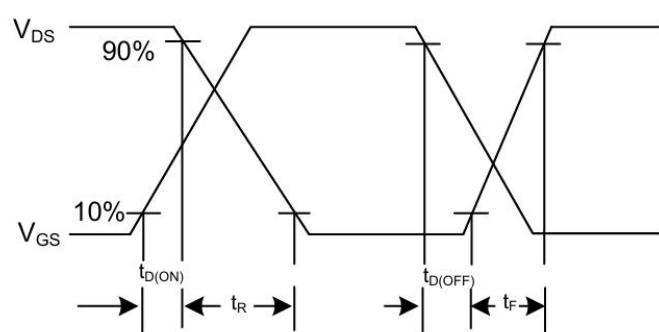
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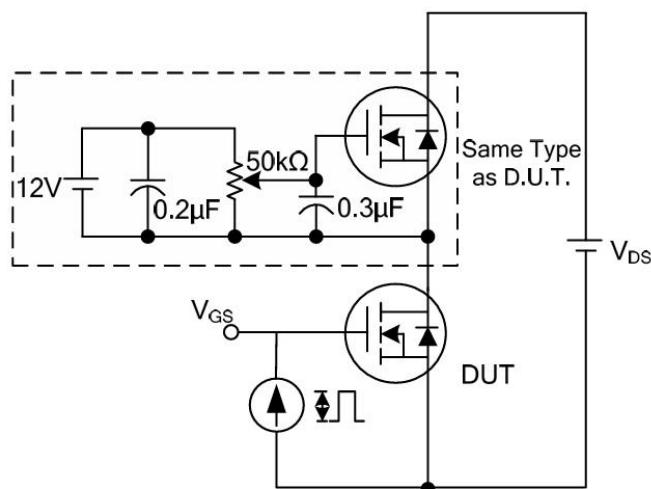
■ TEST CIRCUITS AND WAVEFORMS(Con.t)



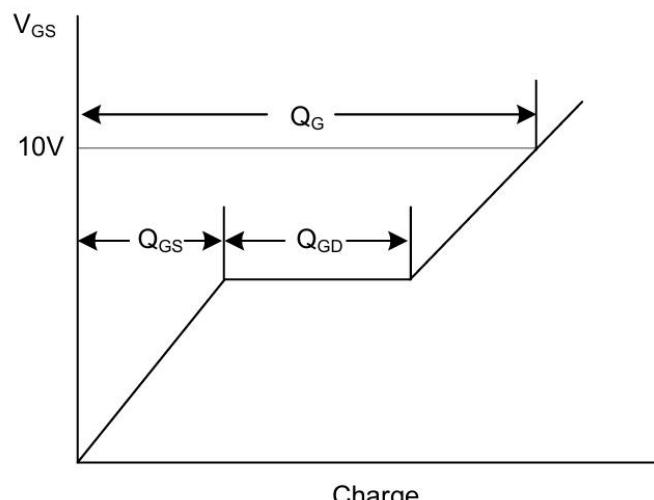
Switching Test Circuit



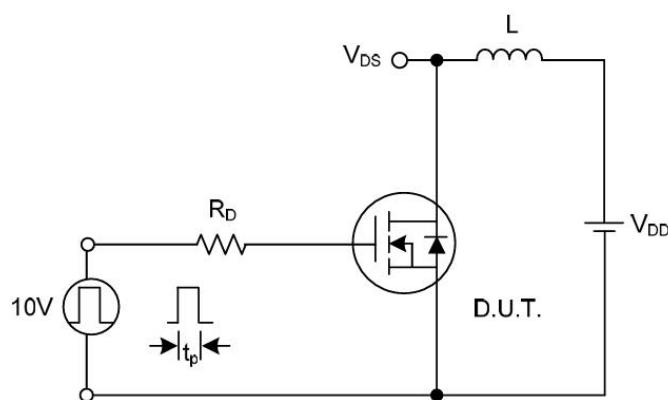
Switching Waveforms



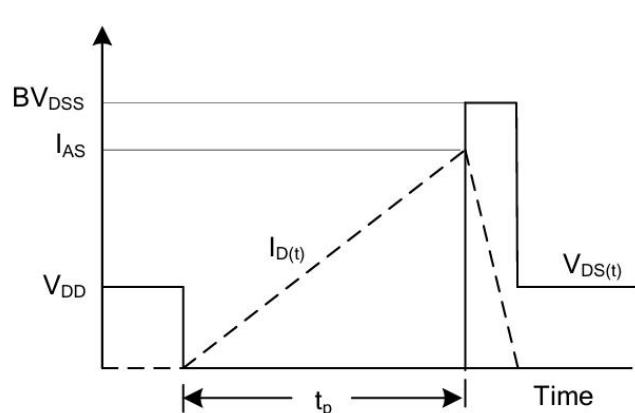
Gate Charge Test Circuit



Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms

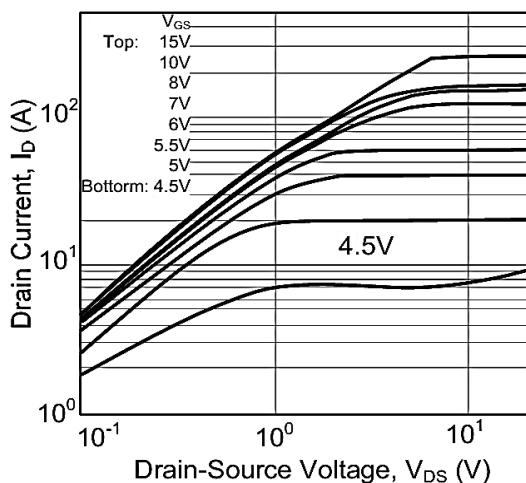


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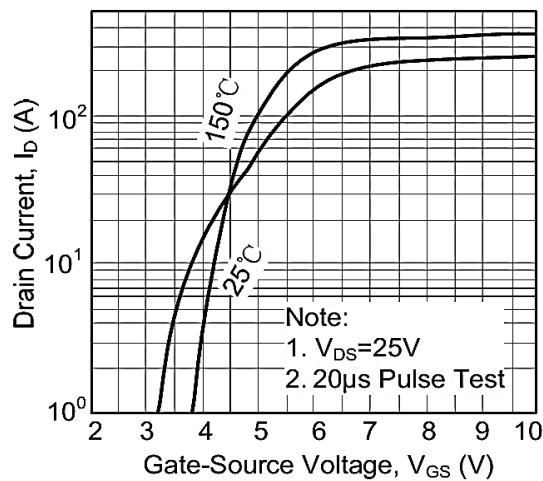
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■ TYPICAL CHARACTERISTICS

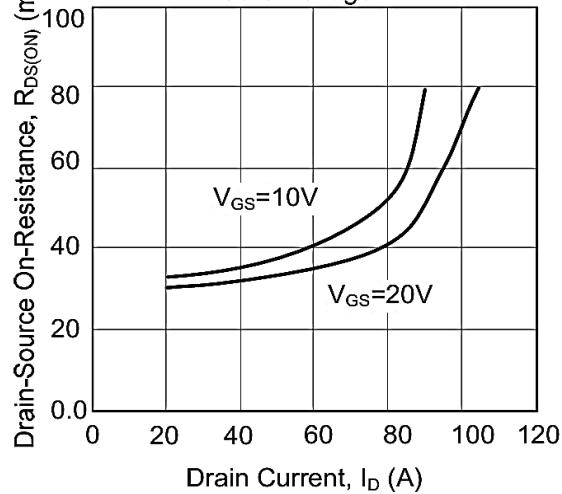
On-State Characteristics



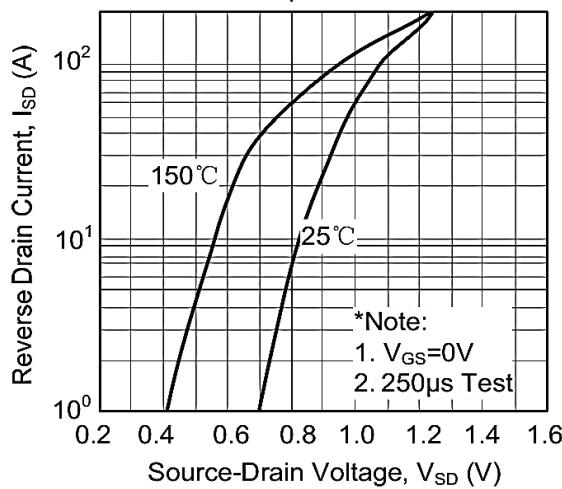
Transfer Characteristics



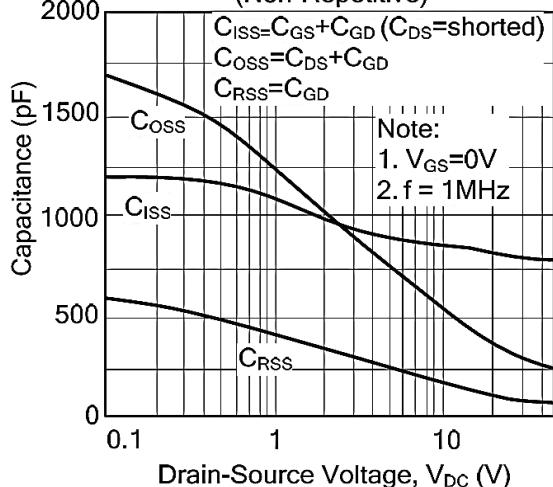
On-Resistance Variation vs. Drain Current and Gate Voltage



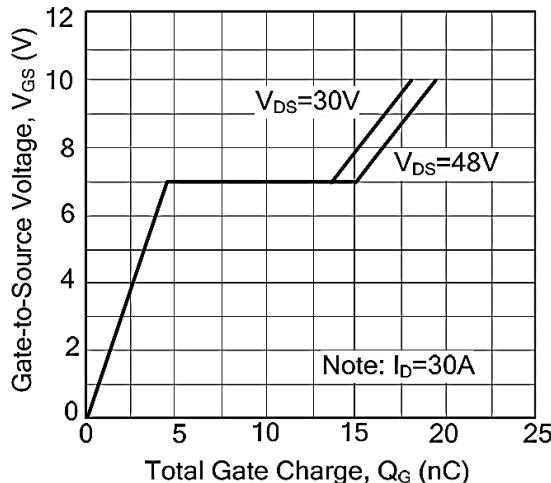
Reverse Drain Current vs. Allowable Case Temperature



Capacitance Characteristics
(Non-Repetitive)



Gate Charge Characteristics

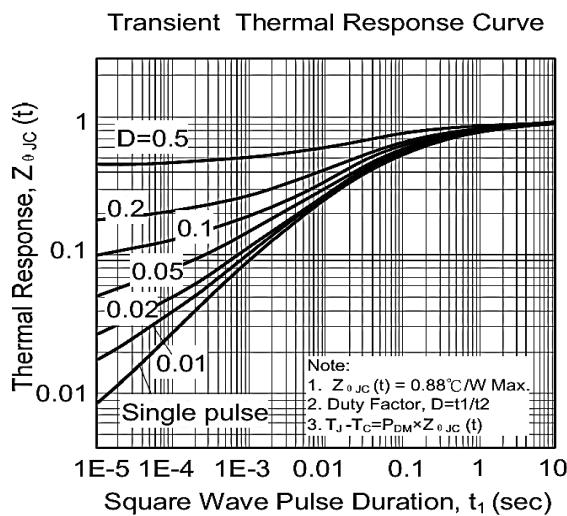
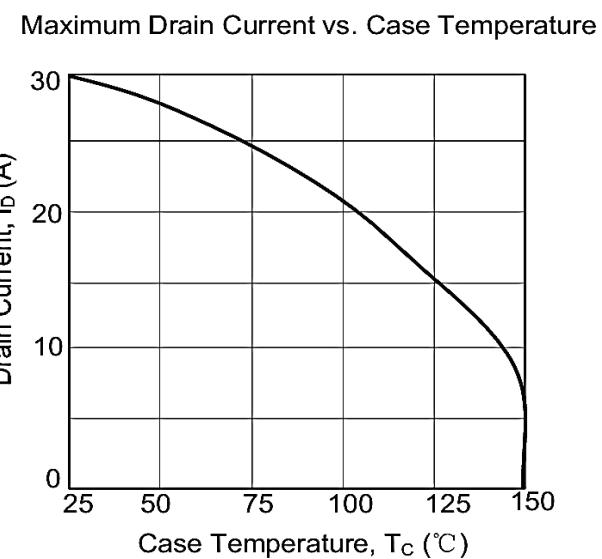
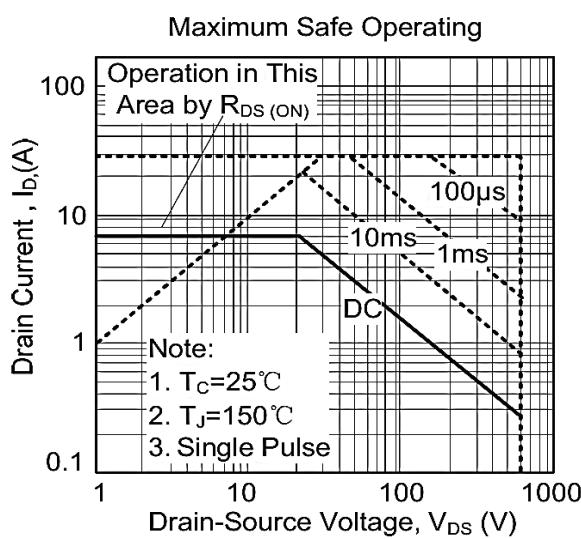
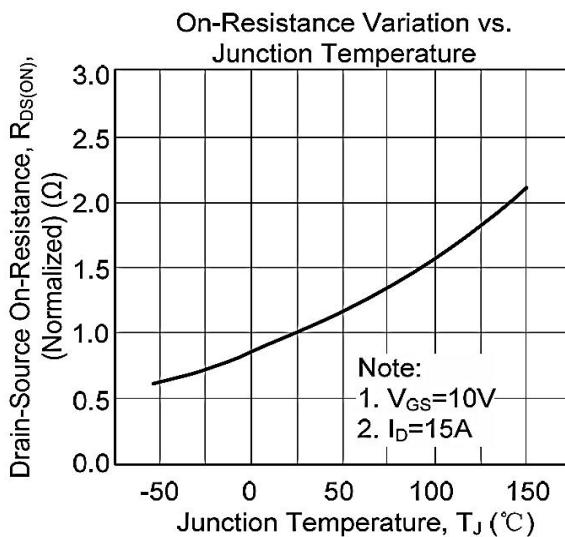
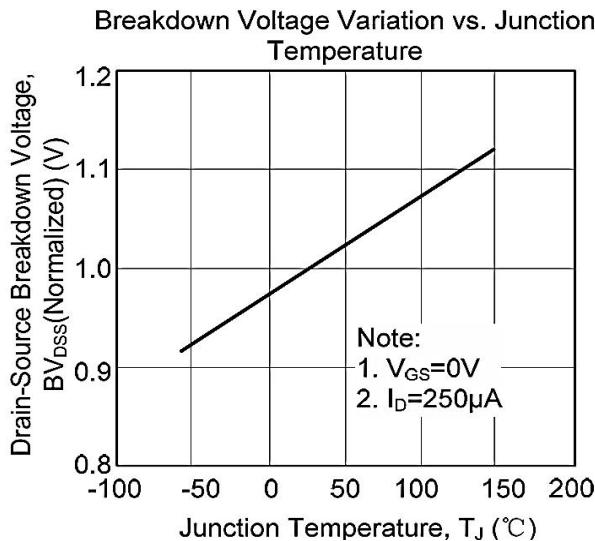




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■ TYPICAL CHARACTERISTICS(Con.t)

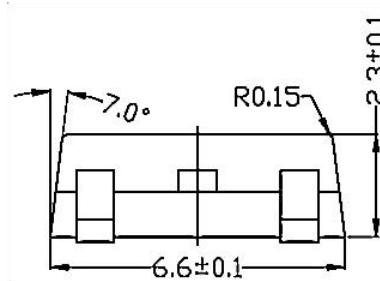
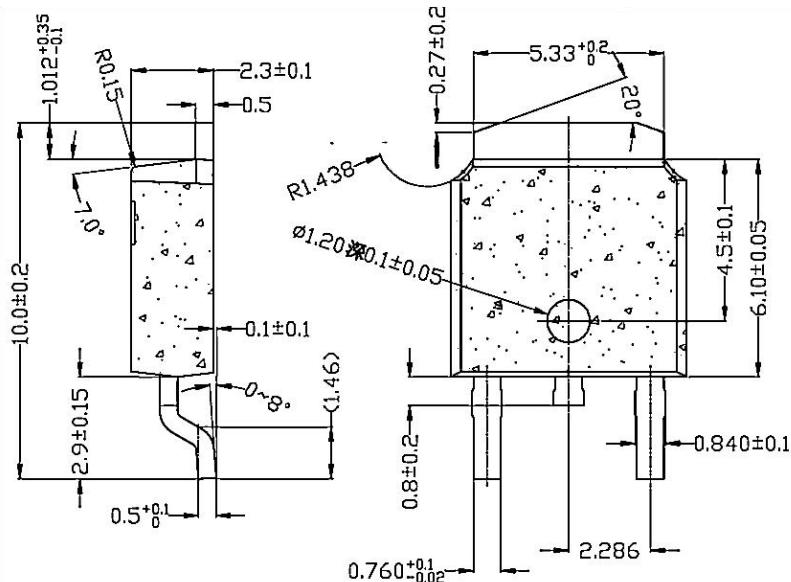




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■ TO - 252 PACKAGE OUTLINE DIMENSIONS



■ TO - 252 PACKING INFORMATION



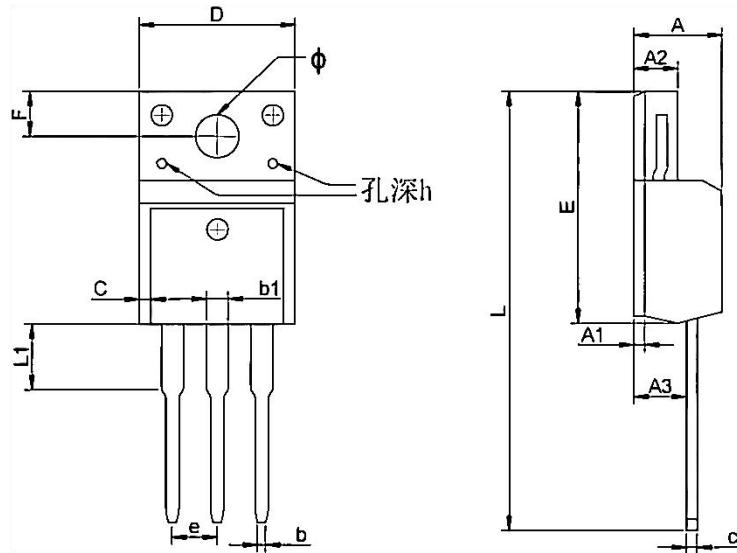
Package version	Reel dimensions $\Phi \times H$ (mm)	Per Reel (pcs)	Reels per box	Inner box dimensions L×W×H (mm)	Outer box (pcs)	Outer box dimensions L×W×H (mm)
T0-252	$\Phi 330 \times 20$	2500	2	360*340*50	25000	375*375*280



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■ TO- 220F PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max	Min	Max
A	4.300	4.750	0.169	0.185
A1	1.830	REF	0.072	REF
A2	2.300	2.850	0.090	0.112
A3	2.500	2.900	0.098	0.114
b	0.400	0.420	0.016	0.016
b1	1.220	1.280	0.048	0.050
C	0.690	0.720	0.027	0.028
c	0.490	0.510	0.019	0.020
D	9.960	10.200	0.392	0.400
E	15.000	15.950	0.588	0.625
e	2.574	TYP	0.101	TYP
F	3.470	REF	0.136	REF
y	3.200	REF	0.125	REF
h	0.000	0.300	0.000	0.012
L	28.780	28.900	1.128	1.133
L1	2.990	3.100	0.117	0.122

■ TO - 220F PACKING INFORMATION



50PCS



5 Inner Box



20 Tube

Outer Box

Inner Box

Package version	Tube dimensions LxWxH (mm)	Per Tube (pcs)	Tube per box	Inner box dimensions LxWxH (mm)	PCS/Inner box	Outer box dimensions LxWxH(mm)	PCS/Outer box
TO-220F	530*32*7	50	20	580*155*50	1000	602*277*188	5000